

VIA[®] CONNECTOR

5G RF board-to-board solution

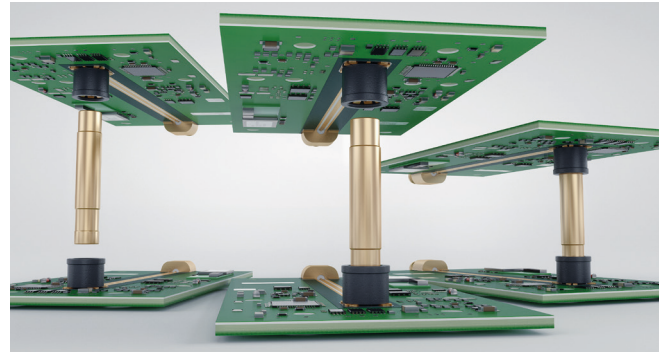
- » Smart board-to-board and board-to-filter solution
- » Excellent blind mate - fast and save assembling
- » Combines all the advantages of board-to-board connections
- » Low mating profile with minimum board-to-board distance of 12 mm



VIA[®] CONNECTOR

5G RF board-to-board solution

VIA[®] (Variable Interface Adapter) is designed for board-to-board and board-to-module RF interconnections. The enhancement of the mechanical design is outstanding: limited detent and smooth bore interfaces are integrated into the adapter – one side of the bullet has mechanical retention to provide limited detent and the other side is smooth bore. Only one PCB type is required for both sides of the connection. For our customers, this results in a lower number of parts on the BOM and lower cost.

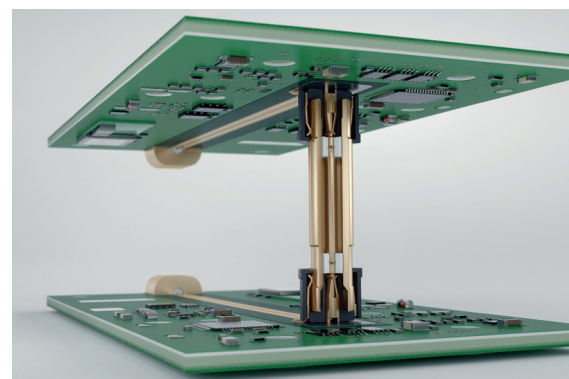


Product Features

- » Combines all the advantages of board-to-board connections (SMP, Longwipe-SMP, P-SMP)
- » Reliable, advanced & secure connection
- » Excellent blind mate – fast and save assembling
- » Same PCB type on both PCB sides simplifies assembling and BOM
- » Limited detent or smooth bore side defined by the bullet adapter
- » Low mating profile with minimum board-to-board distance of 12mm
- » Available as SMD & Thru-Hole component
- » Options for enhanced funnel:
 - » PCB-connector with pre-assembled enhanced funnel
 - » Enhanced funnel assembled by the customer

Characteristics

- » Axial tolerance: ± 1 mm
- » Radial tolerance: 4° : board-to-board distance < 16.5 mm
 ± 0.6 mm: board-to-board distance > 16.5 mm
- » Frequency range: DC to 6 GHz
- » Power: 100 W @ 2.2 GHz @ 20 °C
- » Return loss: ≥ 36 dB (typ.) @ DC to 2.5 GHz depending on axial misalignment



APPLICATIONS

- » Radios and filters in Small Cells
- » Radios and filters in Macro Cells
- » Distributed Antenna Systems (DAS)
- » In-building antennas
- » Massive MIMO antennas
- » Antenna interconnection solutions



Product portfolio

	Picture	Part number (P/N)	Description	Packaging	Plating
PCB types		5400.VIA.2010.003	PCB mount jack	Tape and reel packaging	3 = NiP + Au
		5401.VIA.2010.003	PCB mount jack	Tape and reel packaging	3 = NiP + Au
Adapters		5402.VIA.7910.003	VIA(m) – VIA(m) Adapter, Length 8,5 mm	Bulk packaging	3 = NiP + Au or 5 = Optalloy (optional)
		5403.VIA.7910.003	VIA(m) – VIA(m) Adapter, Length 40 mm	Bulk packaging	3 = NiP + Au or 5 = Optalloy (optional)
		5416.VIAP.8910.005	VIA(m) – VIA(m) Adapter	Bulk packaging	5 = Optalloy
Filter types		5404.VIA.2010.195	Bulkhead jack	Bulk packaging	5 = Optalloy
		5415.VIAP.2010.195	Bulkhead jack	Bulk packaging	5 = Optalloy



EUROPE

IMS Connector Systems GmbH

Phone +49 (0) 7654 901-100
sales@imscs.com

AMERICAS

IMS Connector Systems Inc.

Phone +1 507 837 9393
salesusa@imscs.com

APAC

IMS Connector Systems Ltd.

Phone + 86 (0) 512 6808-1816
sales@imscscn.com

IMS CONNECTOR SYSTEMS

HEADQUARTERS, GERMANY
IMS Connector Systems GmbH
Obere Hauptstraße 30
DE-79843 Löffingen

Phone (+49) 7654 901-100
Fax (+49) 7654 901-199

sales@imscs.com
www.imscs.com

More product information:
www.imscs.com
>>Markets>>Communication

